CyberOptics Introduces Large Particle Sensing Functionality in Next-Generation WaferSense and ReticleSense Airborne Particle Sensors

Advanced APS2 measurement technology incorporates a wider range of particle sizes

CyberOptics' Auto Multi Sensors Named "Best of West" Finalist for SEMICON 2016 by SEMI and Solid State Technology

Minneapolis, MN—June 28, 2016— CyberOptics® Corporation (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, announces it will showcase its next-generation Advanced Airborne Particle Sensors, that incorporate large particle sensing capability. Both the WaferSense® and ReticleSense® Airborne Particle Sensors (APS2, APSR and APSRQ) will be able to measure both small and large particles. Products will be on display at the upcoming SEMICON West 2016, the premier event for the global semiconductor industry, in San Francisco July 12-14, 2016, booth #2323.

CyberOptics' APS2 portfolio improves equipment set-up and long-term yields in semiconductor fabs by wirelessly monitoring airborne particles in real-time. The next-generation APS2 provides even greater versatility, with the industry-leading accuracy and sensitivity valued by semiconductor fabs and equipment OEMs worldwide. The new large particle detecting and measurement functionality covers a range of sizes with four bins for particles larger than 2, 5, 10 and 30 microns.

"We've evolved our widely adopted APS technology portfolio to include large particle measurement capability in the same devices our customers are routinely using to detect and measure small particles," said Subodh Kulkarni, President and CEO of CyberOptics. "Equipment and process engineers can speed equipment qualification, shorten maintenance cycles, and lower equipment expenses with objective and reproducible data – saving our customers time and money with a dual particle measurement capability."

CyberOptics will also demonstrate its WaferSense and ReticleSense Auto Multi Sensors (AMS/AMSR) that measure leveling, vibration, and relative humidity (RH) in an all-in-one wireless real-time device. Recently announced as a **2016 "Best of West" Award Finalist by SEMI and Solid State Technology**, the thin and light form factor enables the AMS to travel through virtually any tool. The AMSR can capture multiple measurements in all locations of the reticle environment. The all-in-one devices are yet another way to increase yield and reduce downtime in semiconductor environments.

About the WaferSense and RetcileSense Line

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS), the Airborne Particle Sensor (APS), the next-generation Airborne Particle Sensor (APS2) and the new Auto Multi Sensor (AMS) are available in various wafer shaped form factors depending on the device, including 150mm, 200mm and 300mm wafer sizes. The ReticleSense measurement portfolio including the Airborne Particle Sensor (APSR & APSRQ) and next-generation APS2, the Auto Leveling System (ALSR) and the new Auto Multi Sensor (AMSR) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; expectations regarding our 2014 acquisition of Laser Design, Inc. (LDI) and its impact on our operations; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

# # #

For additional information, contact:

Lisa Grau, GrauPR, 760-207-9090, lisa@graupr.com

Carla Furanna, CyberOptics, 952-820-5837, cfuranna@cyberoptics.com